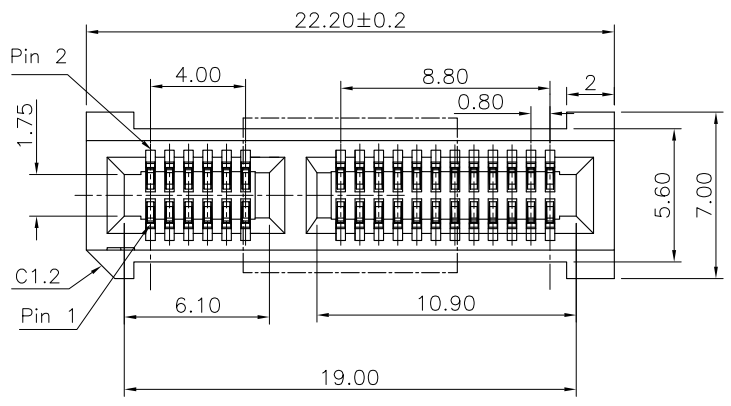


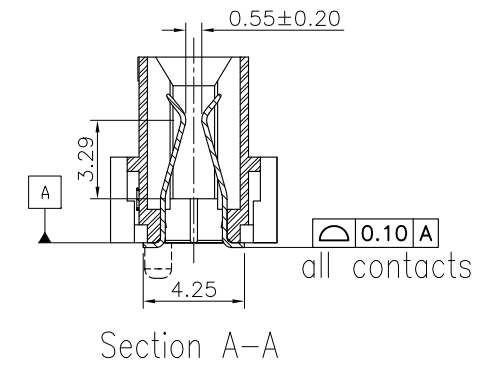
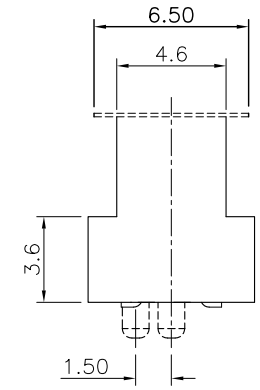
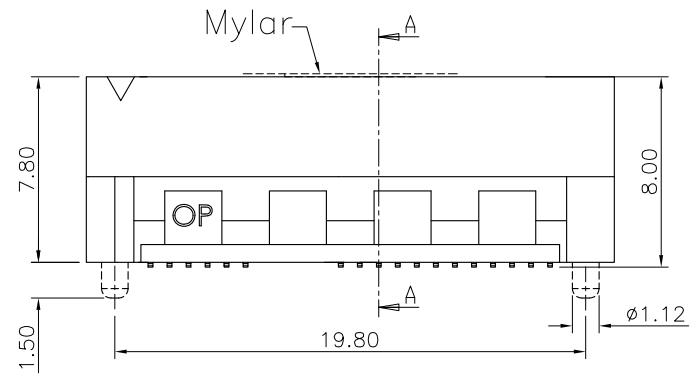
REV.	SPECIFICATION	ECN NO.	APPD.
X2			



**Material and Plating:**  
**Housing:** LCP, 50% Glass Filled, UL94V-0, BLACK.  
**Signal Contacts:** Nickel Copper.  
 30u" gold plated on Contact Area and 80u" Min Tin Plated on Solder Tail over nickel 50u" Min under plated.

**Electrical Characteristics:**  
**Current Rating:** 3.1 AMP.  
**Dielectric Withstanding Voltage:** AC 600V For 1 minute.  
**Insulator Resistance:** 6000MΩ min. at DC 250V.  
**Contact Resistance:** 8.4mΩ max. at DC 100mA.  
**Operating Temperature:** -55°C~+125°C.

**\*RoHS Compliant**  
**Speed:** 28+Gbps @-3dB.



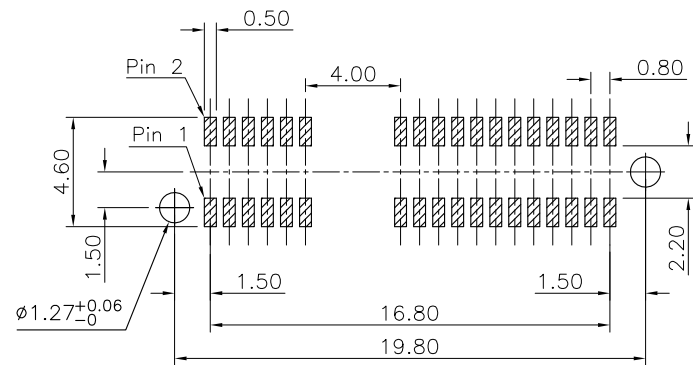
**8206- 2 X 18 C 30 D P 1 T - S**

Series: 8206-  
 Double Row: 2 X  
 Position Per Row: 18  
 C: Selective Gold Plated  
 00: 00μ"  
 10: 10μ"  
 15: 15μ"  
 30: 30μ"  
 D: SMD Type  
 P: With Post  
 N: Without Post  
 T: Tape&Reel Package  
 U: Tube Package  
 1: With Front Key  
 S: Mylar  
 P: Plastic Pad  
 Blank: Without Pad

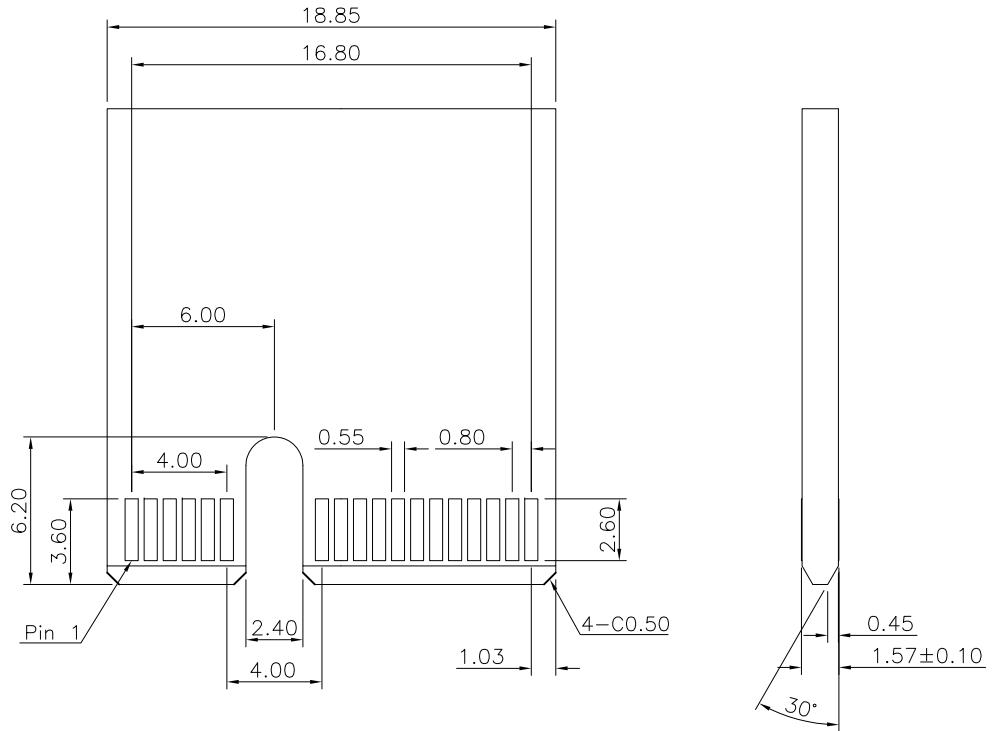
PROPOSAL ONLY

Tolerances	Dwg.No.	8206-D0000-022	Title:	 <b>OUPIN ELECTRONIC(KUNSHAN) CO., LTD.</b> P/N:8206-2X18C30DP1T-S SHEET 1/2 Ver.No. X2
x = ±0.50	Projection		8206 Series Edge Card Connector	
.x = ±0.25	Unit	mm	0.80mm (0.0315") Pitch SMD Type	
.xx = ±0.15	Drawn By	MXM 11/23'17		

REV.	SPECIFICATION	ECN NO.	APPD.
X2			





P. C. Board Layout  
(Tolerance:  $\pm 0.05$ )



RECOMMENDED MATTING BOARD FOOTPRINT  
(Tolerance:  $\pm 0.05$ )

PROPOSAL ONLY

Tolerances	Dwg.No.	8206-D0000-022	Title:		 <b>OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.</b> P/N: 8206-2X18C30DP1T-S			
x = $\pm 0.50$	Projection		8206 Series Edge Card Connector 0.80mm (0.0315") Pitch SMD Type					
.x = $\pm 0.25$	Unit	mm	Scale	1:1				
.xx = $\pm 0.15$	Drawn By	MXM 11/23'17						